

Title (en)

ALLOY POWDER, ALLOY SINTERED COMPACT AND METHOD FOR THEIR PRODUCTION

Title (de)

LEGIERUNGSPULVER, GESINTERTE LEGIERUNGSPELLETS UND VERFAHREN ZU DEREN HERSTELLUNG

Title (fr)

ALLIAGE EN POUDRE, ALLIAGE EN PASTILLES FRITTEES ET PROCEDE DE PRODUCTION

Publication

EP 1118404 A4 20020220 (EN)

Application

EP 99943375 A 19990916

Priority

- JP 9905060 W 19990916
- JP 28889998 A 19980924
- JP 24360399 A 19990830

Abstract (en)

[origin: WO0016937A1] A secondary particle powder (1) having particle diameters of 10 μm to 500 μm is produced by binding particles of a primary particle powder (2) which is made mainly of aluminum and has particle diameters of 5 μm to 300 μm with one another by using an organic binder (3). Similarly, another secondary particle powder having particle diameters of 50 μm to 200 μm is produced by binding particles of a primary particle powder which is made mainly of iron and has particle diameters of 20 μm to 100 μm with one another by using an organic binder. The aforementioned method can be employed for providing an alloy powder having excellent fluidity, and the resulting secondary particle powder can be used for producing an alloy sintered compact having high dimensional accuracy.

IPC 1-7

B22F 1/00

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

- [X] EP 0459114 A1 19911204 - PERKIN ELMER CORP [US]
- [A] US 5429792 A 19950704 - LUK SYDNEY [US]
- [A] PATENT ABSTRACTS OF JAPAN vol. 1998, no. 06 30 April 1998 (1998-04-30)
- See references of WO 0016937A1

Cited by

CN102189253A; US2010310199A1; US9316253B2; EP2366475A1; CN105142830A; EP2988895A4; CN111033215A; EP3674682A4; US11644397B2; US11448578B2; EP3674683A4; WO2014176045A1; US9993872B2

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